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March 2014

FQP12N60C

N-Channel QFET® MOSFET

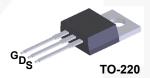
600 V, 12 A, 650 mΩ

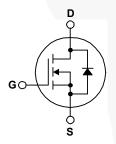
Description

These N-Channel enhancement mode power field effect transistors are produced using Fairchild's proprietary, planar stripe, DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficient switched mode power supplies, active power factor correction, electronic lamp ballast based on half bridge topology.

Features

- 12 A, 600 V, $R_{DS(on)}$ = 650 m Ω (Max.) @ V_{GS} = 10 V, I_D = 6 A
- · Low Gate Charge (Typ. 48 nC)
- · Low Crss (Typ. 21 pF)
- · 100% Avalanche Tested





Absolute Maximum Ratings T_C = 25°C unless otherwise noted.

| Symbol | Parameter | | FQP12N60C | Unit |
|----------------------------------|---|----------|----------------------------------|-----------|
| V _{DSS} | Drain-Source Voltage | | 600 | V |
| I _D | Drain Current - Continuous (T _C = 25°C) - Continuous (T _C = 100°C) | | 12 7.4 | A A |
| I _{DM} | Drain Current - Pulsed | (Note 1) | 48 | A |
| V _{GSS} | Gate-Source voltage | | ± 30 | V |
| E _{AS} | Single Pulsed Avalanche Energy (Note 2) | | 870 | mJ |
| I _{AR} | Avalanche Current (Note 1) | | 12 | А |
| E _{AR} | Repetitive Avalanche Energy (Note 1) | | 22.5 | mJ |
| dv/dt | Peak Diode Recovery dv/dt (Note 3) | | 4.5 | V/ns |
| P_{D} | Power Dissipation $(T_C = 25^{\circ}C)$ - Derate above 25°C | | 225 1.78 | W W/°C |
| T _{J,} T _{STG} | Operating and Storage Temperature Range | | ge Temperature Range -55 to +150 | |
| T _L | Maximum Lead Temperature for Soldering Purpose, 1/8" from Case for 5 Seconds | | 300 | °C |

^{*}Drain current limited by maximum junction temperature

Thermal Characteristics

| Symbol | Parameter | FQP12N60C | Unit | |
|-----------------|---|-----------|------|--|
| $R_{\theta JC}$ | Thermal Resistance, Junction-to-Case, Max. | 0.56 | °C/W | |
| $R_{\theta JA}$ | Thermal Resistance, Junction-to-Ambient, Max. | 62.5 | °C/W | |

Package Marking and Ordering Information

| Part Number | Top Mark | Package | Packing Method | Reel Size | Tape Width | Quantity |
|-------------|-----------|---------|----------------|-----------|------------|----------|
| FQP12N60C | FQP12N60C | TO-220 | Tube | N/A | N/A | 50 units |

Electrical Characteristics T_C = 25°C unless otherwise noted.

| Symbol | Parameter | Conditions | Min | Тур | Max | Unit |
|---|--|--|-----|------|---------|--------------------------|
| Off Charac | teristics | | | ı | ı | |
| BV _{DSS} | Drain-Source Breakdown Voltage | $V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}, T_J = 25^{\circ}\text{C}$ | 600 | | | V |
| ΔBV _{DSS} / ΔT _J | Breakdown Voltage Temperature Coefficient | I _D = 250 μA, Referenced to 25°C | | 0.5 | | V/°C |
| I _{DSS} | Zero Gate Voltage Drain Current | V _{DS} = 600 V, V _{GS} = 0 V V _{DS} = 480 V, T _C = 125° | | | 1 10 | μ Α μ Α |
| I _{GSSF} | Gate-Body Leakage Current, Forward | V _{GS} = 30 V, V _{DS} = 0 V | - | | 100 | nA |
| I _{GSSR} | Gate-Body Leakage Current, Reverse | V _{GS} = -30 V, V _{DS} = 0 V | | | -100 | nA |
| On Charac | teristics | | | | | |
| V _{GS(th)} | Gate Threshold Voltage | $V_{DS} = V_{GS}, I_{D} = 250 \mu A$ | 2.0 | | 4.0 | V |
| R _{DS(on)} | Static Drain-Source On-Resistance | V _{GS} = 10 V, I _D = 6 A | | 0.53 | 0.65 | Ω |
| 9 _{FS} | Forward Transconductance | V _{DS} = 40 V, I _D = 6 A | | 13 | | S |
| Dynamic C | Characteristics | | | | | |
| C _{iss} | Input Capacitance | V _{DS} = 25 V, V _{GS} = 0 V, | \ | 1760 | 2290 | pF |
| C _{oss} | Output Capacitance | f = 1.0 MHz | \ | 182 | 235 | pF |
| C _{rss} | Reverse Transfer Capacitance | | | 21 | 28 | pF |
| Switching | Characteristics | | | | • | |
| t _{d(on)} | Turn-On Delay Time | V _{DD} = 300 V, I _D = 12 A | | 30 | 70 | ns |
| t _r | Turn-On Rise Time | $R_G = 25 \Omega$ | | 85 | 180 | ns |
| t _{d(off)} | Turn-Off Delay Time | | | 140 | 280 | ns |
| t _f | Turn-Off Fall Time | (Note 4) | | 90 | 190 | ns |
| Qg | Total Gate Charge | V _{DS} = 400 V, I _D = 12 A | / | 48 | 63 | nC |
| Q _{gs} | Gate-Source Charge | V _{GS} = 10 V | -/ | 8.5 | | nC |
| Q _{gd} | Gate-Drain Charge | (Note 4) | | 21 | | nC |
| Drain-Soul | rce Diode Characteristics and Maximur | n Ratings | | • | | |
| I _S | Maximum Continuous Drain-Source Dio | de Forward Current | | | 12 | Α |
| I _{SM} | Maximum Pulsed Drain-Source Diode F | orward Current | | | 48 | Α |
| V_{SD} | Drain-Source Diode Forward Voltage | V _{GS} = 0V, I _S = 12 A | | | 1.4 | V |
| t _{rr} | Reverse Recovery Time | V _{GS} = 0V, I _S = 12 A | | 420 | | ns |
| Q _{rr} | Reverse Recovery Charge | dl _F /dt = 100 A/μs | | 4.9 | | μС |

NOTES:

^{1.} Repetitive rating: pulse-width limited by maximum junction temperature.

^{2.} L = 11 mH, I_{AS} = 12 A, V_{DD} = 50 V, R_G = 25 Ω , starting T_J = 25°C.

 $^{3.}I_{SD} \le 12$ A, di/dt ≤ 200 A/ μ s, $V_{DD} \le BV_{DSS}$, starting T_J = 25°C.

^{4.} Essentially independent of operating temperature typical characteristics.

Typical Performance Characteristics

Figure 1. On-Region Characteristics

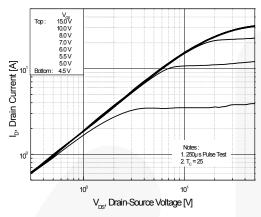


Figure 3. On-Resistance Variation vs. **Drain Current and Gate Voltage**



Figure 2. Transfer Characteristics

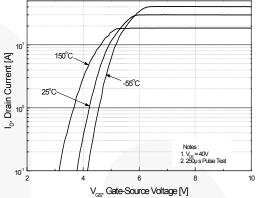
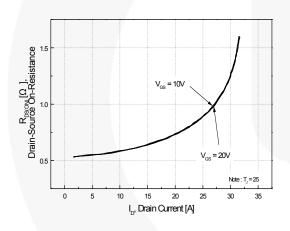


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperatue



Reverse Drain Current [A] V_{sp}, Source-Drain voltage [V]

Figure 5. Capacitance Characteristics

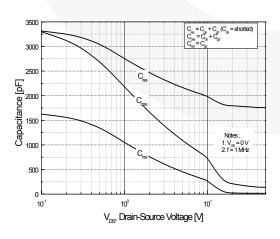
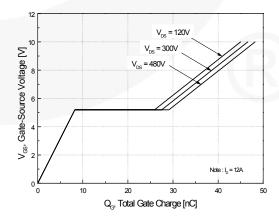


Figure 6. Gate Charge Characteristics



Typical Performance Characteristics (Continued)

Figure 7. Breakdown Voltage Variation vs. Temperature

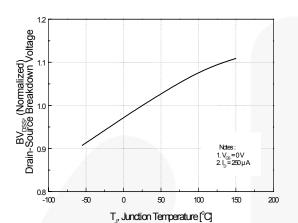


Figure 8. On-Resistance Variation vs. Temperature

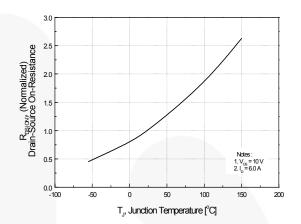
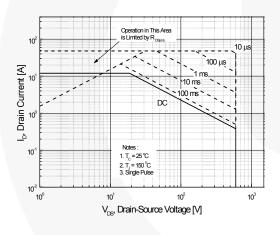


Figure 9. Maximum Safe Operating Area





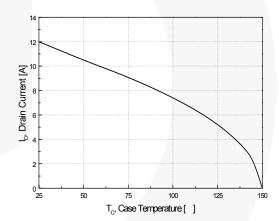
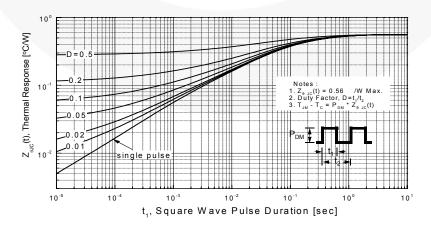


Figure 11. Transient Thermal Response Curve



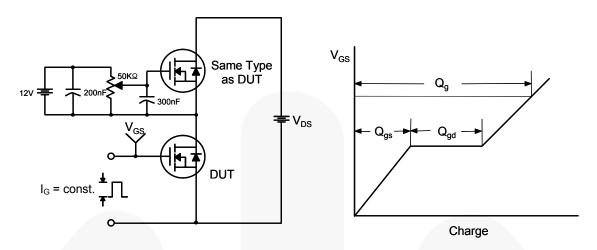


Figure 12. Gate Charge Test Circuit & Waveform

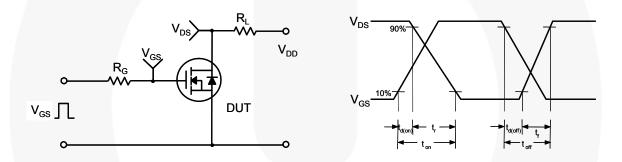


Figure 13. Resistive Switching Test Circuit & Waveforms

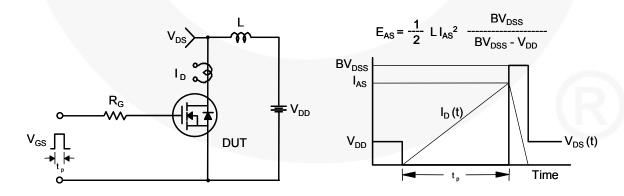


Figure 14. Unclamped Inductive Switching Test Circuit & Waveforms

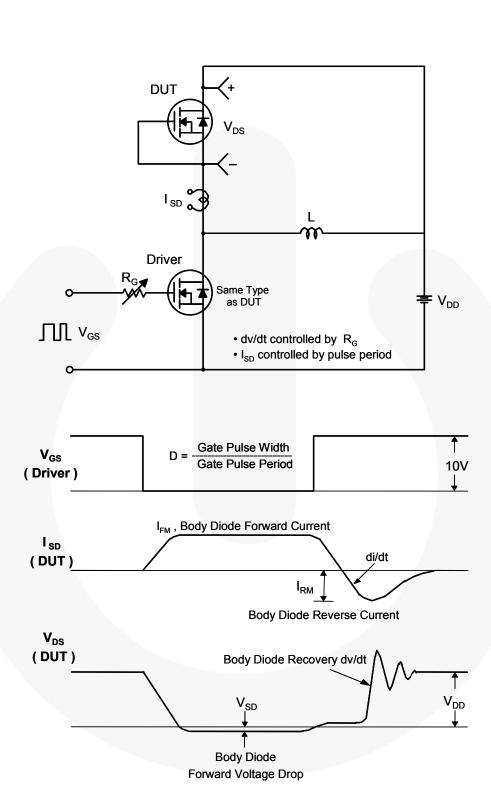


Figure 15. Peak Diode Recovery dv/dt Test Circuit & Waveforms

Mechanical Dimensions

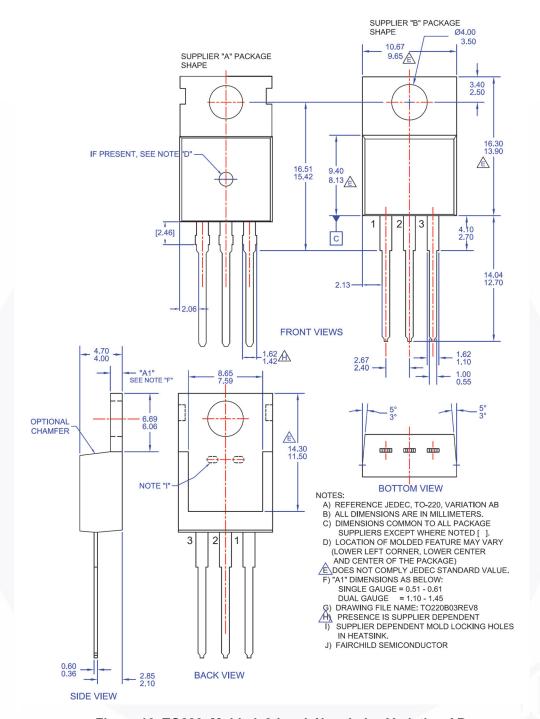


Figure 16. TO220, Molded, 3-Lead, Non Jedec Variation AB

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